



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Redline, et al.

Docket No. 2156-056

Serial No.: 09/251,641

Group No.: 1741

Filed: February 17, 1999

Examiner: W. Nicolas

Title: Method for Enhancing One Solderability of A Surface

Honorable Commissioner of Patents and Trademarks
Washington, DC 20231

PRELIMINARY AMENDMENT

In conjunction with the continued prosecution application of the foregoing patent application please take the following amendment and remarks into consideration.

IN THE CLAIMS

9. (Amended) An immersion silver plating solution comprising (i) a soluble source of silver ions, (ii) an acid and (iii) an additive selected from the group consisting of fatty amines, fatty amides, quaternary salts, [amphatic] amphoteric [sales] salts, resinous amines, resinous amides, fatty acids, ethoxylated versions of any of the foregoing, propoxylated versions of any of the foregoing and mixtures of any of the foregoing.

REMARKS

Claims 1-8 and 17-20 are pending. Claim 17 has been amended. The Examiner had previously rejected claims 1-8 and 17-20 under 35 U.S.C. 103 (a) as being unpatentable over Ferrier, et al. (EP 0797380 A1) in view of Wakita (5,567,357).

In this regard the Examiner had found that Ferrier teaches a process and immersion plating solution comprising a soluble source of silver ions and an acid but

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